

Electronic Filing System (EFS) Data Electronic Patent Application Submission USPTO Use Only

REINFORCED DIE PAD SUPPORT

EFS ID:

53070

Application ID:

10669820

Title of Invention:

STRUCTURE

First Named Inventor:

Chung Tzu

Domestic/Foreign Application:

Domestic Application

Filing Date:

2003-09-24

Effective Receipt Date:

2004-01-02

Submission Type:

Information Disclosure

Statement

Filing Type:

Confirmation number:

5197

Attorney Docket Number:

AMKOR090A

Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark

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TRANSMITTAL

Electronic Version v1.1 Stylesheet Version v1.1.0

Title of Invention

REINFORCED DIE PAD SUPPORT STRUCTURE

Application Number:

10/669820

Date:

2003-09-24

First Named Applicant:

Chung Hsing Tzu

Confirmation Number:

5197

Attorney Docket Number: AMKOR090A

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Submitted by:	Elec. Sign.	Sign. Capacity	
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney	

Documents being submitted

Files

us-ids

ids5-usidst.xml

us-ids.dtd

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Comments

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

REINFORCED DIE PAD SUPPORT STRUCTURE

Application Number:

10/669820

Confirmation Number:

5197

First Named Applicant:

Chung Tzu

Attorney Docket Number: AMKOR090A

Art Unit:

2811

Search string:

(6197615 or 6198171 or 6201186 or 6201292 or 6204554 or 6208020 or 6208021 or 6208023 or 6211462 or 6218731 or 6222258 or 6225146 or 6229200 or 6229205 or 6239367 or 6239384 or 6242281 or 6256200 or 6258629 or 6281566 or 6281568 or 6282095 or 6285075 or 6291271 or 6291273 or 6294100 or 6294830 or 6295977 or 6297548 or 6303984 or 6303997 or 6307272 or 6309909 or 6316822 or 6316838 or 6323550 or 6326243 or 6326244 or 6326678 or 6335564 or 6337510 or 6339255 or 6348726 or 6355502 or 6369447 or 6369454 or 6373127 or 6380048

or 6384472 or 6388336).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Signature

Examiner Name	Date		